



Material Content Data Sheet



Sales Product Name		BSL308C H6327		Issued		24. January 2018		
MA#		MA001189494						
Package		PG-TSOP6-6-4		Weight*		14.90 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.009	0.06		592	
	noble metal	gold	7440-57-5	0.034	0.23		2296	
	inorganic material	silicon	7440-21-3	0.522	3.50	3.79	35021	37909
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		95	
	non noble metal	titanium	7440-32-6	0.007	0.05		475	
	non noble metal	chromium	7440-47-3	0.021	0.14		1425	
	non noble metal	copper	7440-50-8	7.048	47.29	47.49	472896	474891
wire	non noble metal	copper	7440-50-8	0.131	0.88	0.88	8776	8776
encapsulation	organic material	carbon black	1333-86-4	0.066	0.44		4421	
	plastics	epoxy resin	-	1.417	9.51		95055	
	inorganic material	silicondioxide	60676-86-0	5.106	34.26	44.21	342639	442115
leadfinish	non noble metal	tin	7440-31-5	0.392	2.63	2.63	26335	26335
plating	noble metal	silver	7440-22-4	0.149	1.00	1.00	9974	9974
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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